


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F103VBI6	Y0MJ*410YYY1	A	9993	2017-03-13
Amount		UoM	Unit type	ST ECOPACK Grade
63.91		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7x0.6	100	NAC	
Comment	UFBGA 7x7x0.60 100L R12sq P0.5			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	YOMJ*410YYY1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	2.254	mg	supplier	die	Silicon (Si)	7440-21-3		1.972	mg	874889	30856
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	12866	454
Die or Dies				supplier	metallization	Cobalt (Co)	7440-48-4		0.027	mg	11979	422
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	3549	125
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.016	mg	7098	250
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.019	mg	8429	297
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.183	mg	81189	2863
Mold compound		36.375	mg	supplier	Mold compound	Silica, vitreous [Fused Silica]	60676-86-0		32.159	mg	884096	503192
Mold compound				supplier	Mold compound	Epoxy resins	Trade Secret		1.466	mg	40302	22939
Mold compound				supplier	Mold compound	Phenolic resins	Trade Secret		1.100	mg	30241	17212
Mold compound				supplier	Mold compound	Carbon black	1333-86-4		0.183	mg	5031	2863
Mold compound				supplier	Mold compound	Metal Hydroxide	Trade Secret		1.100	mg	30241	17212
Mold compound				supplier	Mold compound	Other miscellaneous substances	Trade Secret		0.367	mg	10089	5742
Substrate		19.539		supplier	Core	organic resin	Trade Secret		1.714	mg	87722	26819
Substrate				supplier	Core	Silicon dioxide	7631-86-9		0.969	mg	49593	15162
Substrate				supplier	Core	Other inorganic filler	Trade Secret		0.969	mg	49593	15162
Substrate				supplier	Core	Glass fiber	65997-17-3		3.800	mg	194483	59459
Substrate				supplier	Solder mask	Organic resin	Trade Secret		1.970	mg	100824	30825
Substrate				supplier	Solder mask	Inorganic filler	Trade Secret		1.061	mg	54302	16601
Substrate				supplier	Cu Coil	Copper	7440-50-8		5.594	mg	286299	87529
Substrate				supplier	Ni Plating	Nickel	7440-02-0		3.007	mg	153897	47051
Substrate				supplier	Ni Plating	Gold	7440-57-5		0.455	mg	23287	7119
Die attach		0.792		supplier	Glue	Resins	Trade Secret		0.356	mg	449495	5570
Die attach				supplier	Glue	Phenol-formaldehyde polymer	9003-35-4		0.079	mg	99747	1236
Die attach				supplier	Glue	Silica	67762-90-7		0.016	mg	20202	250
Die attach				supplier	Glue	Proprietary Material	Trade Secret		0.341	mg	430556	5336
Wire		1.112		supplier	Gold wire	Gold	7440-57-5		1.112	mg	1000000	17399
Solderball		3.838		supplier	Solder	Tin	7440-31-5		3.704	mg	965086	57957
Solderball				supplier	Solder	Silver	7440-22-4		0.134	mg	34914	2097